


# MATERIAL DECLARATION SHEET



Material Number	CR01005 Series			
Product Line	Thick Film Chip Resistors			
Compliance Date	2018/03/26			
RoHS Compliant	Yes	MSL	1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1.	Ceramic Substrate	Ceramic	0.0320606	Aluminum oxide	1344-28-1	96%	81.00%	84.37%
				Silicon dioxide	14808-60-7	4%	3.37%	
2.	Conductor Layer	Silver conductor	0.0007486	Silver	7440-22-4	95%	1.87%	1.97%
				Glass (non-lead)	65997-17-3	5%	0.10%	
3.	Resistive Element	Resistor	0.0002090	Ruthenium dioxide	12036-10-1	25%	0.14%	0.55%
				Silver	7440-22-4	40%	0.22%	
				Palladium	7440-05-3	15%	0.08%	
				Lead	7439-92-1	20%	0.11%	
4.	Over Coating	Epoxy	0.0006992	Epoxy	25068-38-6	100%	1.84%	1.84%

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5.	End Terminal	NiCr alloy	0.0001102	Nickel	7440-02-0	80%	0.23%	0.29%
				Chromium	7440-47-3	20%	0.06%	
6.	Ni Plating	Ni	0.0022040	Nickel	7440-02-0	100%	5.80%	5.80%
7.	Sn Plating	Sn	0.0019684	Tin	7440-31-5	100%	5.18%	5.18%
		TOTAL WEIGHT	0.038					

**This Document was updated on:** 3/26/2018

**Important remarks:** It is the responsibility of the user to verify they are accessing the latest version.